

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hyung-Gon Kim	03/28/2006
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., Ltd
Street Address:	416 Maetan-dong, Yeongtong-gu
Internal Address:	Suwon-Si
City:	Gyeonggi-do
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11279067
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	5649-1895
NAME OF SUBMITTER:	Susan E. Freedman
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

CH \$40.00 11279067

ASSIGNMENT

THIS ASSIGNMENT, made by me, **Hyung-Gon Kim**, a citizen of the Republic of Korea, residing at 229-4, Seongnae-2dong, Gangdong-gu, Seoul, Republic of Korea;

WITNESSETH: That,

WHEREAS, I am the sole inventor of certain new and useful improvements in **NAND FLASH MEMORY DEVICES AND METHODS OF LSB/MSB PROGRAMMING THE SAME**, for which an application has been filed, or is being concurrently filed, in the United States Patent and Trademark Office. I hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known or to file this Assignment concurrently with the application; and


WHEREAS, **Samsung Electronics Co., Ltd.**, a Korean corporation having a principal place of business at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by these presents do hereby sell, assign, transfer, and convey unto the said assignee, its successors and assigns, the entire right, title, and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues or other forms of protection thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted along with any term extensions thereon or therefor, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made.

I hereby request that said Letters Patent be issued in accordance with this assignment.

I further covenant and agree that, at the time of the execution and delivery of these presents, I possess full title to the invention and application above-mentioned, and that I have the unencumbered right and authority to make this assignment.

I further covenant and agree to communicate to said assignee or its representatives any facts known to me relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors, or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns, and other legal representatives; and I hereby instruct, and further covenant and agree to bind my heirs, legal representatives, and assigns, to do same, without further compensation, but at the expense of said assignee or its representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 28 day of March, 2006
 (SEAL)
Hyung-Gon Kim

Witnessed by:

Date: _____

Date: _____